

FIGURE 1A

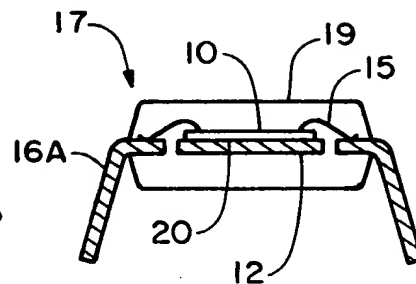


FIGURE 1B

**PROVIDING A CONVENTIONAL SEMICONDUCTOR DIE
AND LEADFRAME, STEP A.**

**DISPENSING AN INSTANT CURING ADHESIVE
MATERIAL ON THE LEADFRAME (OR ALTERNATELY ON
THE DIE), STEP B.**

**PLACING THE DIE IN CONTACT WITH THE ADHESIVE
MATERIAL, STEP C.**

**POLYMERIZING THE ADHESIVE MATERIAL TO FORM A
CURED ADHESIVE LAYER AND BOND THE DIE TO THE
LEADFRAME, STEP D.**

FIGURE 2

APPLIED U.S. PATENT
 BY CLASS SUBCLASS
 DRAFTSMAN

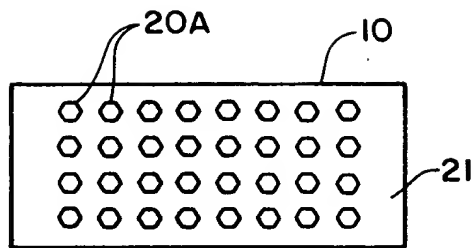


FIGURE 3A

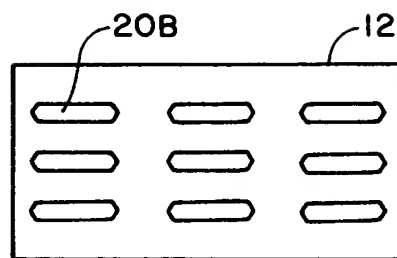


FIGURE 3B

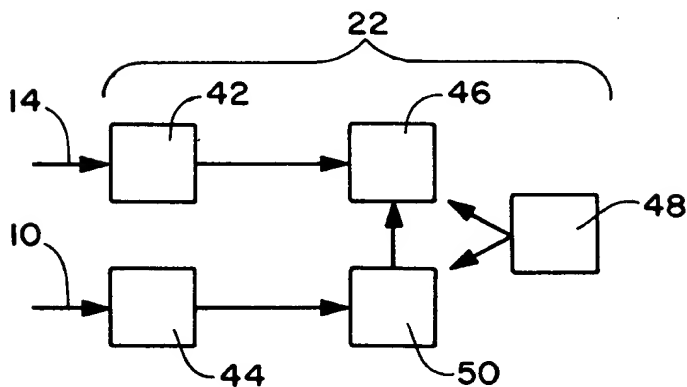


FIGURE 4

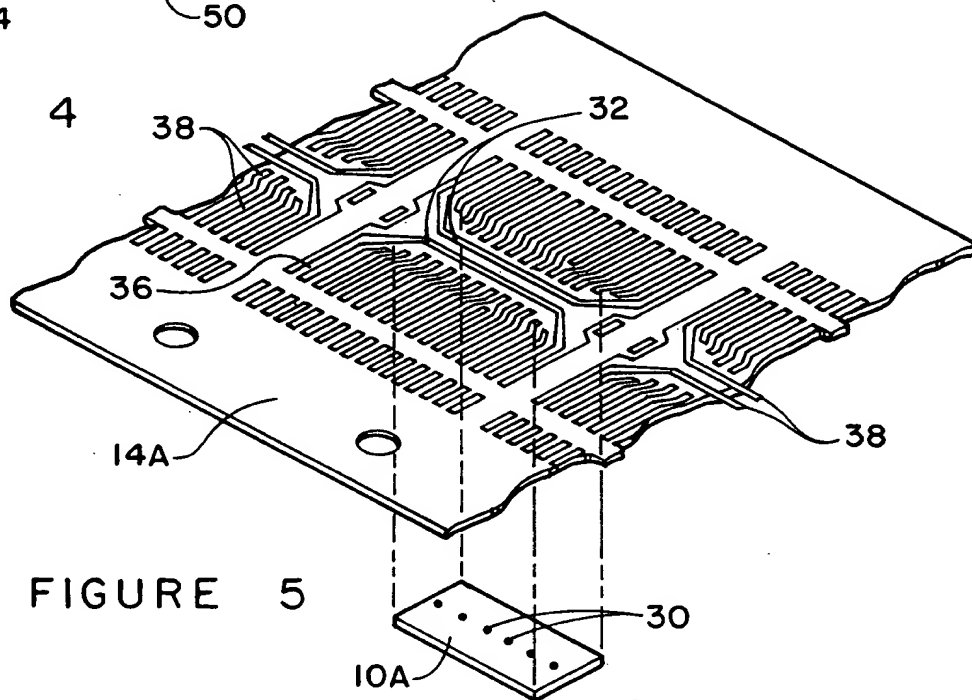


FIGURE 5

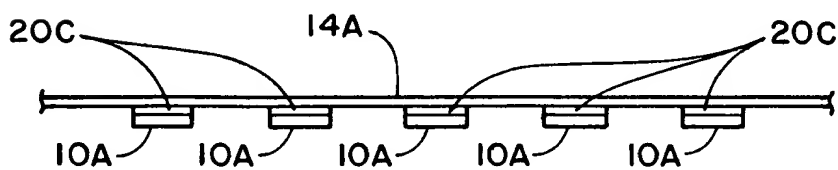


FIGURE 6